AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application. Please cancel claim 7 without prejudice and amend claims 9, 10, 12 and 15-17 as follows:

LISTING OF CLAIMS:

Claims 1-6   cancelled

Claim 7.   (Cancelled)

Claim 8.   (Previously Amended) A method for manufacturing electronic devices obtained by equipping with electronic component chips on a printed circuit board and so forth, comprising the steps of:

supplying a plurality of electronic component chips in an aligned relationship; and cleaning outer surfaces of the electronic component chips;

wherein said step of supplying a plurality of electronic component chips comprises the steps of:

supplying a plurality of electronic component chips by a hopper;

transferring a plurality of electronic component chips by a buffer portion; and

feeding a plurality of electronic component chips one at a time by a chute portion disposed in the rear stage of the buffer portion,

and wherein said step of cleaning outer surfaces of the electronic component chips is provided between said step of transferring a plurality of electronic component chips by a buffer portion and said step of feeding a plurality of electronic component chips by a chute portion.

Claim 9.   (Currently Amended) A method according to Claim [[7]] 8, wherein

said step of cleaning ~~external electrodes~~ outer surfaces of the electronic component

chips comprises a process of grinding outer surfaces of electronic component chips.

Claim 10.   (Currently Amended) A method according to Claim 9, wherein the

process of grinding ~~external electrodes~~ outer surfaces of electronic component chips

is carried out with an abrasive belt and a driving source for driving the abrasive belt.

Claim 11.   (Original) A method according to Claim 10, wherein said step of

transferring a plurality of electronic component chips is provided with a transferring

belt for transferring electronic component chips and the transferring belt serves as

well as the abrasive belt.

Claim 12.   (Currently Amended) A method according to Claim [[7]] 8, wherein

said step of cleaning ~~external electrodes~~ outer surfaces of the electronic component

chips is performed by washing outer surfaces of electronic component chips using a

washing liquid.

Claim 13.   (Previously Presented) A method according to Claim 8, wherein said

step of cleaning outer surfaces of the electronic component chips comprises a

process of grinding outer surfaces of electronic component chips.

Claim 14.   (Previously Presented) A method according to Claim 8, wherein said

step of cleaning outer surfaces of the electronic component chips is performed by

washing outer surfaces of electronic component chips using a washing liquid.

Claim 15.   (Currently Amended) A method according to Claim 9, wherein said

step of cleaning ~~external electrodes~~ <u>outer surfaces</u> of the electronic component chips

is performed by washing outer surfaces of electronic component chips using a

washing liquid.

Claim 16.   (Currently Amended) A method according to Claim 10, wherein said

step of cleaning ~~external electrodes~~ <u>outer surfaces</u> of the electronic component chips

is performed by washing outer surfaces of electronic component chips using a

washing liquid.

Claim 17.   (Currently Amended) A method according to Claim 11, wherein said

step of cleaning ~~external electrodes~~ <u>outer surfaces</u> of the electronic component chips

is performed by washing outer surfaces of electronic component chips using a

washing liquid.

Claim 18.   (Previously Presented) A method for manufacturing electronic devices

obtained by at least maintaining electronic component chips on a printed circuit

board, comprising the steps of:

supplying a plurality of electronic component chips in an aligned relationship,

wherein aligned electronic component chips are taken out one at a time from

a chute portion connected to a buffer portion; and

cleaning external electrodes of the electronic component chips.